Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	431	intel.as. and wire and (die ic chip) same (contact pad)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 09:24
L2	1183	257/786 and wire same (die ic chip) same (contact pad)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 09:27
L3	1322	257/786 and wire same (die ic chip) same (contact pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 09:27
L4	1191	257/786 and wire with (die ic chip) same (contact pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 09:27
L5	1110	257/786 and wire with (die ic chip) with (contact pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 09:28